

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1-10. (Cancelled)

11. (Currently amended) A package with electronic circuitry, comprising:

a first card comprising at least one protruding receptacle, each protruding receptacle having a respective open side;

a conductive protective layer mated adjacent to said first card such that said protective layer spans across each said open side; and

a second card comprising at least one closed cell and electronic circuitry with a dielectric overlay, wherein said dielectric overlay is printed on said second card and spans at least a portion of said electronic circuitry, and further wherein the dielectric circuit overlay is patterned so as to follow and cover the electrical circuitry;

wherein said second card is ~~mated~~ positioned relative to said first card such that said dielectric overlay is adjacent to said protective layer and each said closed cell is breachably aligned with a respective said open side.

12. (Original) The package of claim 11, wherein said cards are non-conductive.

13. (Previously presented) The package of claim 11, wherein at least a portion of said at least one receptacle is pliable.

14. (Previously presented) The package of claim 11, wherein said second card includes an electronic monitoring device receiving area in communication with said circuitry.

15. (Canceled)

16. (Currently amended) The package of claim 11, wherein a respective portion of said circuitry spans a ~~given~~ corresponding said closed cell.

17. (Canceled)

18. (Canceled)

19. (Previously presented) The package of claim 11 further comprising a third card, said third card comprising at least one open cell, wherein said at least one protruding receptacle is matingly nested within said at least one open cell.

20. (Previously presented) The package of claim 19, wherein said third card further comprises a locking tab, said locking tab being configured to releasably retain said package within an outer sleeve.

21. (Previously presented) The package of claim 11, wherein said dielectric overlay exactly follows and covers said electronic circuitry.

22. (Currently amended) The package of claim 11, wherein said electronic circuitry is carried on a circuitry side of said second card, said dielectric overlay being carried on ~~covering~~ said circuitry side of said second card.

23. (Currently amended) A package, comprising:

a blister card defining at least one blister cell, each blister cell having a blister opening, each blister opening being associated with a first side of the blister card;

a metal foil backing attached directly to the first side of the blister card, the metal foil backing sealing each blister opening; and

a trace card mounted against the metal foil backing, the trace card carrying electrical circuitry and a dielectric circuit overlay, the dielectric circuit overlay covering the electrical circuitry, the dielectric circuit overlay being positioned

between the metal foil backing and the electrical circuitry, the dielectric circuit overlay being patterned so as to follow and cover the electrical circuitry, at least [[a]] one respective portion of the electrical circuitry being breachably aligned with a given corresponding blister opening.

24. (Previously presented) The package of claim 23, wherein the blister card and the metal foil backing together retain at least one dose of medication.

25. (Cancelled)

26. (Previously presented) The package of claim 23, further comprising a third card having at least one open cell, the third card being mounted atop the blister card, each blister cell matingly received through a respective open cell of the third card.

27. (Previously presented) The package of claim 26, wherein said third card further comprises a locking tab, the locking tab being configured to releasably retain the package within an outer sleeve.